



# **DIRECTPATH™**, 2Vrms Line Driver with Adjustable gain

#### **FEATURES**

- DIRECTPATH™
  - Eliminates Pop/Clicks
  - Eliminates Output DC-Blocking Capacitors
  - Provides Flat Frequency Response 20Hz–20kHz
- Low Noise and THD
  - SNR > 102 dB
  - Typical  $V_N$  < 15  $\mu$ Vms
  - THD+N < 0.05% 20 Hz-20 kHz</li>
- 2Vrms Output Voltage into 2.5 kΩR Load With 3.3V Supply Voltage
- Differential Input

#### **APPLICATIONS**

- Set-Top Boxes
- PDP / LCD TV
- Blu-ray Disc™, DVD-Players
- Home Theater in a Box

#### **DESCRIPTION**

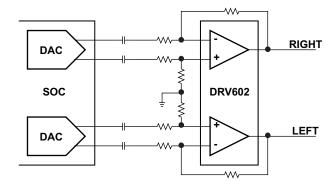
The DRV602PW is a 2Vrms Pop-less stereo line driver designed to allow the removal of the output dc-blocking capacitors for reduced component count and cost. The device is ideal for single supply electronics where size and cost are critical design parameters.

Designed using TI's patented DIRECTPATH<sup>TM</sup> technology, the DRV602 is capable of driving 2Vrms into a  $2.5k\Omega$  load with 3.3V supply voltage. The device has differential inputs and uses external gain setting resistors, that supports a gain range of  $\pm 1V/V$  to  $\pm 10V/V$ . The use of external gain resistors also allows the implementation of a 2nd order low pass filter to compliment DAC's and SOC converters. The line output of the DRV602 has  $\pm 8kV$  IEC ESD protection. The DRV602 (referred to as the '602) has build-in shutdown control for pop-free on/off control.

Using the DRV602 in audio products can reduce component count compared to traditional methods of generating a 2Vrms output. The DRV602 doesn't require a power supply greater than 3.3V to generate its 5.6V<sub>PP</sub> output, nor does it require a split rail power supply. The DRV602 integrates its own charge pump to generate a negative supply rail that provides a clean, pop-less ground biased 2Vrms output.

The DRV602 is available in a 14 pin TSSOP package.

If higher SNR, trimmed DC-offset and external undervoltage-mute functions are beneficial in the application, TI recommends the footprint compatible DRV603 (SLOS617).





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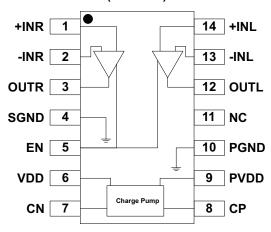
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These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

# PW (TSSOP) PACKAGE (TOP VIEW)



#### **PIN FUNCTIONS**

PIN		I/O <sup>(1)</sup>	DECORIDATION		
NAME	TSSOP (PW)	1/0	DESCRIPTION		
+INR	1	I	Right channel OPAMP positive input		
-INR	2	I	Right channel OPAMP negative input		
OUTR	3	0	Right channel OPAMP output		
SGND	4	I	Signal ground		
EN	5	I	Enable input, active high		
VDD	6	0	Supply voltage		
CN	7	I/O	Charge pump flying capacitor negative terminal		
СР	8	I/O	Charge pump flying capacitor positive terminal		
PVDD	9	I	Positive supply		
PGND	10	I	Power ground		
NC	11		No internal connection		
OUTL	12	0	Left channel OPAMP output		
-INL	13	I	Left channel OPAMP negative input		
+INL	14	I	Left channel OPAMP positive input		

(1) I = input, O = output, P = power

Product Folder Link(s): DRV602



# **ABSOLUTE MAXIMUM RATINGS**(1)(2)

over operating free-air temperature range

		VALUE	UNIT
	Supply voltage, VDD to GND	–0.3 V to 5.5	٧
$V_{I}$	Input voltage	$V_{SS} - 0.3$ to $V_{DD} + 0.3$	٧
$R_{L}$	Minimum load impedance	> 600	Ω
	EN to GND	-0.3 to V <sub>DD</sub> +0.3	٧
$T_{J}$	Maximum operating junction temperature range,	0 to 70	°C
T <sub>stg</sub>	Storage temperature range	-40 to 150	°C
ESD	IEC Contact ESD Protection per IEC6100-4-2, on output pins measured on DRV602EVM	±8	kV

<sup>(1)</sup> Stresses beyond those listed under absolute maximum ratings may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under recommended operating conditions is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

#### **ORDERING INFORMATION**

T <sub>A</sub>	PACKAGE <sup>(1)</sup>	DESCRIPTION
0°C to 70°C	DRV602PW	14-Pin TSSOP

<sup>(1)</sup> For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI website at www.ti.com.

# RECOMMENDED OPERATING CONDITIONS

			MIN	TYP	MAX	UNIT
$V_{DD}$	Supply voltage,	DC Supply Voltage	3	3.3	4.5	V
$V_{IH}$	High-level input voltage	EN		60		% of VDD
$V_{IL}$	Low-level input voltage	EN		40		% of VDD
T <sub>A</sub>	Operating free-air temperature		0		70	°C

#### **ELECTRICAL CHARACTERISTICS**

 $T_A = 25$ °C (unless otherwise noted)

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
V <sub>OS</sub>	Output offset voltage	V <sub>DD</sub> = 3 V to 4.5 V, Voltage follower - gain = 1			5	mV
PSRR	Supply Rejection Ratio	V <sub>DD</sub> = 3.3 V to 4.5 V		88		dB
$V_{OH}$	High-level output voltage	$V_{DD} = 3.3 \text{ V}, R_L = 2.5 \text{ k}\Omega$	3.10			V
V <sub>OL</sub>	Low-level output voltage	$V_{DD} = 3.3 \text{ V}, R_L = 2.5 \text{ k}\Omega$			-3.05	V
I <sub>IH</sub>	High-level input current (EN)	$V_{DD} = 4.5 \text{ V}, V_I = V_{DD}$			1	μΑ
$ I_{1L} $	Low-level input current (EN)	$V_{DD} = 4.5 \text{ V}, V_{I} = 0 \text{ V}$			1	μΑ
		$V_{DD}$ = 3.3 V, No load, EN = $V_{DD}$	8	11		mA
I <sub>DD</sub>	Supply Current	$V_{DD}$ = 4.5 V, No load, EN = $V_{DD}$		12.5	20	ША
		Shutdown mode, Vdd = 3 V to 4.5 V			2	mA

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<sup>(2)</sup> These voltages represents the DC voltage + peak AC waveform measured at the terminal of the device in all conditions.

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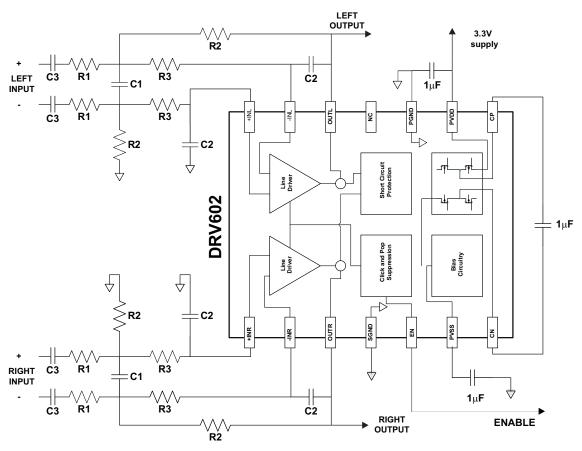


#### **OPERATING CHARACTERISTICS**

 $V_{DD}=3.3~V~,~T_{A}=25^{\circ}C,~R_{L}=2.5k\Omega,~C_{(PUMP)}=C_{(PVSS)}=1~\mu F~,~C_{IN}=1~\mu F,~R_{IN}=33~k\Omega,~R_{fb}=68k\Omega~(unless~otherwise~noted)$ 

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
Vo	Output Voltage (Outputs In Phase)	THD = 1%, V <sub>DD</sub> = 3.3 V, f = 1 kHz		2.05		Vrms
THD+N	Total harmonic distortion plus noise	V <sub>O</sub> = 2 Vrms, f = 1 kHz V <sub>O</sub> = 2 Vrms, f = 6.8 kHz		0.01% 0.05%		
	Crosstalk	V <sub>O</sub> = 2 Vrms, f = 1 kHz		-80		dB
Io	Output current limit	V <sub>DD</sub> = 3.3 V		20		mA
R <sub>IN</sub>	Input resistor range		1	10	47	kΩ
R <sub>fb</sub>	Feedback resistor range		4.7	20	100	kΩ
	Slew rate			4.5		V/μs
	Maximum capacitive load			220		pF
$V_N$	Noise output voltage	A-weighted, BW 20Hz–22kHz		15		$\mu V rms$
SNR	Signal to noise ratio	$V_O$ = 2 Vrms, THD+N = 0.1%, 22 kHz BW, A-weighted		102		dB
G <sub>BW</sub>	Unity Gain Bandwidth			8		MHz
A <sub>VO</sub>	Open-loop voltage gain			150		dB
Fcp	Charge Pump frequency		225	450	675	kHz

# **APPLICATION CIRCUIT**



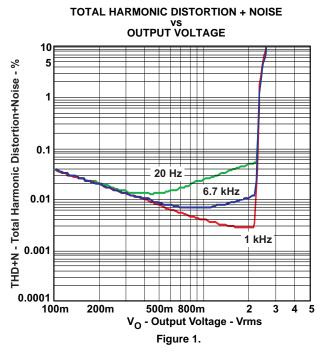
 $R1=33k\Omega,\,R2=68k\Omega,\,R3=100k\Omega,\,C1=150pF,\,C2=15pF,\,C3=1~\mu F$ 

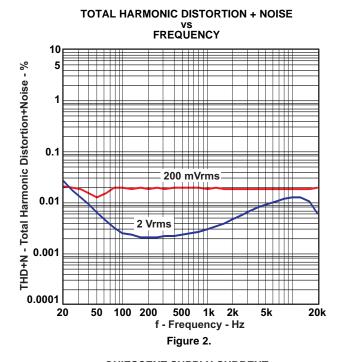
Differential input, single ended output, 2nd order filter. 40kHz –3dB frequency, Gain 2.06.

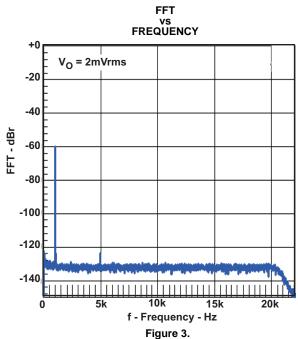


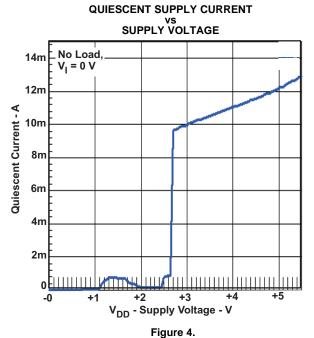
# **TYPICAL CHARACTERISTICS**

 $V_{DD} = 3.3 V \text{ , TA} = 25 ^{\circ}\text{C, } C_{(PUMP)} = C_{(PVSS)} = 1 \ \mu\text{F , } C_{IN} = 1 \ \mu\text{F, } R_{IN} = 33 \ k\Omega, \ R_{fb} = 68 \ k\Omega \text{ (unless otherwise noted)}$ 











#### APPLICATION INFORMATION

# **Line Driver Amplifiers**

Single-supply line driver amplifiers typically require dc-blocking capacitors. The top drawing in Figure 5 illustrates the conventional line driver amplifier connection to the load and output signal.

DC blocking capacitors are often large in value, and a mute circuit is needed during power up to minimize click & pop. The output capacitor and mute circuit consume PCB area and increase cost of assembly, and can reduce the fidelity of the audio output signal.

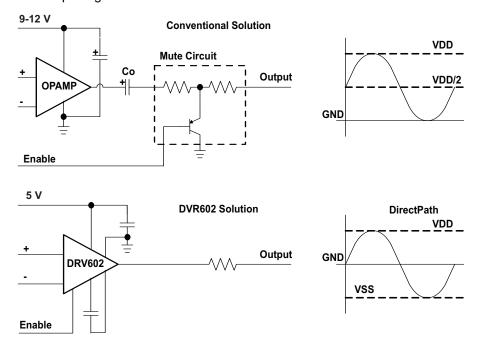


Figure 5. Conventional and DirectPath Line Driver

The DirectPath™ amplifier architecture operates from a single supply, but makes use of an internal charge pump to provide a negative voltage rail.

Combining the user provided positive rail and the negative rail generated by the IC, the device operates in what is effectively a split supply mode.

The output voltages are now centered at zero volts with the capability to swing to the positive rail or negative rail. The DirectPath amplifier requires no output dc blocking capacitors.

The bottom block diagram and waveform of Figure 5 illustrate the ground-referenced Line Driver architecture. This is the architecture of the DRV602.



# **Charge Pump Flying Capacitor and PVSS Capacitor**

The charge pump flying capacitor serves to transfer charge during the generation of the negative supply voltage. The PVSS capacitor must be at least equal to the charge pump capacitor in order to allow maximum charge transfer. Low ESR capacitors are an ideal selection, and a value of  $1\mu F$  is typical. Capacitor values that are smaller than  $1\mu F$  can be used, but the maximum output voltage may be reduced and the device may not operate to specifications.

#### **Decoupling Capacitors**

The DRV602 is a DirectPath Line Driver amplifier that require adequate power supply decoupling to ensure that the noise and total harmonic distortion (THD) are low. A good low equivalent-series-resistance (ESR) ceramic capacitor, typically  $1\mu F$ , placed as close as possible to the device  $V_{DD}$  lead works best. Placing this decoupling capacitor close to the DRV602 is important for the performance of the amplifier. For filtering lower frequency noise signals, a 10- $\mu F$  or greater capacitor placed near the audio power amplifier would also help, but it is not required in most applications because of the high PSRR of this device.

# Gain setting resistors ranges

The gain setting resistors,  $R_{IN}$  and  $R_{fb}$ , must be chosen so that noise, stability and input capacitor size of the DRV602 is kept within acceptable limits. Voltage gain is defined as  $R_{fb}$  divided by  $R_{IN}$ .

Selecting values that are too low demands a large input ac-coupling capacitor,  $C_{IN}$ . Selecting values that are too high increases the noise of the amplifier. Table 1 lists the recommended resistor values for different gain settings.

Table 1	l. Recommende	ed Resistor	Values

INPUT RESISTOR VALUE, R <sub>IN</sub>	FEEDBACK RESISTOR VALUE, R <sub>fb</sub>	DIFFERENTIAL INPUT GAIN	INVERTING INPUT GAIN	NON INVERTING INPUT GAIN
22 kΩ	22 kΩ	1.0 V/V	-1.0 V/V	2.0 V/V
15 kΩ	30 kΩ	1.5 V/V	-1.5 V/V	2.5 V/V
33 kΩ	68 kΩ	2.1 V/V	-2.1 V/V	3.1 V/V
10 kΩ	100 kΩ	10.0 V/V	-10.0 V/V	11.0 V/V

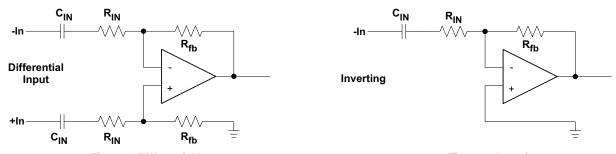


Figure 6. Differential Input

Figure 7. Inverting

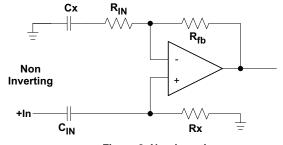


Figure 8. Non-Inverting

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## Input-Blocking Capacitors

DC input-blocking capacitors are required to be added in series with the audio signal into the input pins of the DRV602. These capacitors block the DC portion of the audio source and allow the DRV602 inputs to be properly biased to provide maximum performance. The input blocking capacitors also limit the DC gain to 1, limiting the DC-offset voltage at the output.

These capacitors form a high-pass filter with the input resistor,  $R_{IN}$ . The cutoff frequency is calculated using Equation 1. For this calculation, the capacitance used is the input-blocking capacitor and the resistance is the input resistor chosen from Table 1, then the frequency and/or capacitance can be determined when one of the two values are given.

$$fc_{IN} = \frac{1}{2\pi R_{IN} C_{IN}}$$
 or  $C_{IN} = \frac{1}{2\pi fc_{IN} R_{IN}}$  (1)

# Using the DRV602 as 2<sup>nd</sup> Order Filter

Several audio DACs used today require an external low-pass filter to remove out of band noise. This is possible with the DRV602 as it can be used like a standard OPAMP.

Several filter topologies can be implemented both single ended and differential. In Figure 9, a Multi FeedBack - MFB, with differential input and single ended input is shown.

An ac-coupling capacitor to remove dc-content from the source is shown, it serves to block any dc content from the source and lowers the dc-gain to 1 helping reducing the output dc-offset to minimum.

The component values can be calculated with the help of the TI FilterPro<sup>™</sup> program available on the TI website at: http://focus.ti.com/docs/toolsw/folders/print/filterpro.html

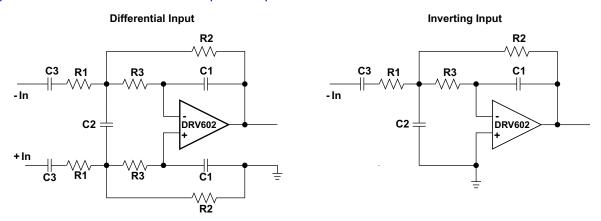


Figure 9. 2<sup>nd</sup> Order Active Low Pass Filter

The resistor values should have a low value for obtaining low noise, but should also have a high enough value to get a small size ac-coupling cap. With the proposed values, 33k, 68k, 100k, a DNR of 102dB can be achieved with a small  $1\mu$ F input ac-coupling capacitor.

8



# **Pop-Free Power Up**

Pop-free power up is ensured by keeping the  $\overline{SD}$  (shutdown pin) low during power supply ramp up and down. The EN pin should be kept low until the input ac-coupling capacitors are fully charged before asserting the EN pin high, this way proper precharge of the ac-coupling is performed, and pop-less power-up is achieved. Figure 10 illustrates the preferred sequence.

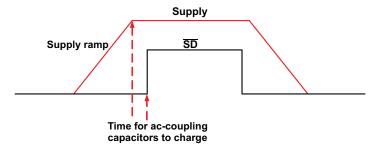


Figure 10. Power-Up Sequence

# **Capacitive Load**

The DRV602 has the ability to drive a high capacitive load up to 220pF directly, higher capacitive loads can be accepted by adding a series resistor of  $10\Omega$  or larger. The figure below shows a 10kHz signal into a 470pF capacitor using the 10R series resistor.

## **Layout Recommendations**

A proposed layout for the DRV602 can be seen in the DRV602EVM user's guide (SLOU248) and the Gerber files can be downloaded on www.ti.com, open the DRV602 product folder and look in the Tools and Software folder.

The gain setting resistors,  $R_{\text{IN}}$  and  $R_{\text{fb}}$ , must be placed close to the input pins to minimize the capacitive loading on these input pins and to ensure maximum stability of the DRV602. For the recommenced PCB layout, see the DRV602EVM user's guide.



## PACKAGE OPTION ADDENDUM

1-Jan-2009

#### **PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
DRV602PW	ACTIVE	TSSOP	PW	14	90	TBD	Call TI	Call TI
DRV602PWR	ACTIVE	TSSOP	PW	14	2000	TBD	Call TI	Call TI

<sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

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(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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# PW (R-PDSO-G\*\*)

#### 14 PINS SHOWN

# PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

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